

Title (en)

MOULD FOR SOLDERING, ARRANGEMENT OF MOULDS, A METHOD AND A COMPONENT

Title (de)

FORMKÖRPER ZUM LÖTEN, ANORDNUNG VON FORMKÖRPERN, EIN VERFAHREN SOWIE EIN BAUTEIL

Title (fr)

CORPS MOULÉS UTILISÉS DANS LES OPÉRATIONS DE BRASAGE, ENSEMBLE DE CORPS MOULÉS, PROCÉDÉ ET ÉLÉMENT APPROPRIÉS

Publication

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Application

EP 09756484 A 20091119

Priority

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Abstract (en)

[origin: EP2196276A1] The flat molding body (4) comprises continuous passages formed from an upper side to a lower side of the molding body by perforations or bores and formed by an open porosity in a sponge-like manner. The molding body is formed as double-T-piece, puzzle piece and presintered flat material. The T-beam (13) of the double-T-piece has an additional hooking (16). The molding body consists of metal or metal alloy. The puzzle piece is removable as convexly and/or concavely limited flat polygon body with a contiguous flat coating and leaves gaps between individual polygon bodies. The flat molding body (4) comprises continuous passages formed from an upper side to a lower side of the molding body by perforations or bores and formed by an open porosity in a sponge-like manner. The molding body is formed as double-T-piece, puzzle piece and presintered flat material. The T-beam (13) of the double-T-piece has an additional hooking (16). The molding body consists of metal or metal alloy. The puzzle piece is removable as convexly and/or concavely limited flat polygon body with a contiguous flat coating and leaves gaps between individual polygon bodies. The convex and concave portions of the individual puzzle pieces allow a positive hooking of the individual puzzle pieces to the contiguous flat coating. Independent claims are included for: (1) an arrangement of several molding bodies; (2) a method for soldering a component; and (3) a component.

IPC 8 full level

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CPC (source: EP US)

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